PATENT 25213

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re U.S. F	atent Application	3,
Applicant: S	Shigeru Okamoto)
Divisional o Serial No. (I hereby certify that this paper is being deposited with the United States Postal Service as EXPRESS MAIL in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 2023 1, on 03/08/00
Filed: Octol	ber 29, 1997	Express Label No.: EL409491078US Signature:
CON AND	EDDED ELECTRO- DUCTIVE LAYER METHOD FOR MATION THEREOF	F-CLASS.WCM Appr. February 20, 1998)
Art Unit:	2823))
Examiner:	Eaton, K.))

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. §§1.56, 1.97 and 1.98, Applicant through counsel herewith submits copies of the publications as set forth in the attached form PTO-1449 as follows:

U.S. DOCUMENTS

4,990,997	Nishida	Feb. 5, 1991
5,070,036	Stevens	Dec. 3, 1991
5,290,733	Hayasaka et al.	Mar. 1, 1994
5,464,666	Fine et al.	Nov. 7, 1995
5,489,548	Nishioka et al.	Feb. 6, 1996
5,552,341	Lee	Sep. 3, 1996
5,614,756	Forouhi et al.	Mar. 25, 1997
5,627,102	Shinriki et al.	May 6, 1997
5,641,985	Tamura et al.	Jun. 24, 1997
5,652,464	Liao et al.	Jul. 29, 1997
5,739,579	Chiang et al.	Apr. 14, 1998
5,793,057	Summerfelt	Aug. 11, 1998
5,801,095	Huang et al.	Sep. 1, 1998
5,801,098	Fiordalice et al.	Sep. 1, 1998
5,903,053	Lijima et al.	May 11, 1999

OTHER DOCUMENTS

John A.T. Norman, David A. Roberts et al., ENHANCED DEPOSITION OF COPPER FILMS BY CVD - Advanced Metalization for ULSI Application pp. 57-62

Susan L. Cohen, Michael Liehr and Srinandan Kasi, Mechanisms of copper chemical vapor depositions, Appl. Phys. Lett. 60 (1), January 6, 1992, pp. 50-52

Applicant respectfully requests that the Examiner consider the above-listed references in the examination of this application and list these references of record in the application.

Respectfully submitted

GREER_BURNS & CRAIN, LTD.

By

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